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Global SiC CMP Pads Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global SiC CMP Pads market size was valued at US$ 81.28 million in 2025 and is forecast to a readjusted size of US$ 238 million by 2032 with a CAGR of 16.7% during review period.

Chemical mechanical polishing/planarization (CMP) is a process that removes materials by a combination of chemical and mechanical (or abrasive) actions to achieve highly smooth and planar material surfaces. Chemical-mechanical polishing (CMP) is often associated with chemical-mechanical planarization which is a polishing process assisted by chemical reactions to remove surface materials. CMP is a standard manufacturing process practiced at the semiconductor industry to fabricate integrated circuits and memory disks. When the purpose is to remove surface materials, it is referred to as chemical-mechanical polishing. However, when the purpose is to flatten a surface, it is referred to as chemical-mechanical planarization. CMP is considered to be a tribochemical process because of the synergy between friction and corrosion. CMP Pad (Chemical Mechanical Polishing Pad) is a product which increases semiconductor integration by smoothening the semiconductor wafer surface through physical and chemical polishing processes.

SiC CMP pads are polishing pads used in the Chemical Mechanical Planarization (CMP) process for semiconductor manufacturing, specifically for Silicon Carbide (SiC) wafers. CMP is a process used to smooth and flatten the surface of a semiconductor wafer to ensure that the layers of material deposited during fabrication are evenly distributed. This is especially important for high-performance devices such as power semiconductors, which use SiC due to its superior thermal conductivity and electrical properties.

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SiC wafers are harder and more challenging to polish than traditional silicon wafers, so specialized CMP pads are designed to handle the mechanical and chemical stresses involved. These pads are typically made from materials like polyurethane, which have a good balance of hardness and flexibility, and are optimized to work with specific slurry solutions in the CMP process.

The primary role of SiC CMP pads is to ensure that the wafer surface is planarized, with minimal damage or defects, in order to produce high-quality SiC devices, such as those used in power electronics or high-frequency applications.

The silicon carbide (SiC) chemical mechanical planarization (CMP) pads market is evolving rapidly, driven by the booming demand for SiC power devices in electric vehicles (EVs), renewable energy, and 5G infrastructure. Below are the key industry trends shaping the future of SiC CMP pads.

The current market-oriented enterprises in China have not obtained foreign certifications, so there is no export for the time being. Because downstream companies are mainly concentrated in Japan, Taiwan, South Korea, Europe and United States and other countries. The electronics industry is mainly concentrated in the Asia-Pacific region, but the current political situation is not optimistic, it may be the most serious year for China's political crisis in the past 30 years. Due to the current trade frictions and China's current international political factors, it may be the best time for domestic SiC CMP Pads manufacturers to occupy the market, and the country's policy investment will increase in the coming years. Therefore, Chinese companies will usher in opportunities for localization in the next few years. We predict that in order to occupy the market, Hubei Dinglong may actively lower the price of the product and madly occupy the market.

At present, considering the cost and the influence of the size of silicon wafers on the performance and efficiency of integrated circuits, the increase in the size of wafers is an inevitable trend and a mainstream trend, in particular, 8-inch and 12-inch. Wafer may develop in the direction of 18 inches in the future. However, the larger the size, the more difficult it is to produce the corresponding CMP pad. When the downstream size becomes an inevitable trend, in order to occupy the market, it is necessary to be able to develop large-size pad, otherwise it will be eliminated by the market. With the expectation of the superior performance improvement of integrated circuits, the polishing performance of CMP pads has to be increased, so its performance in the future must be more stringent.

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The global key companies of SiC CMP Pads include DuPont, Fujibo Group, Entegris, IVT Technologies, and etc. In 2024, the global three largest players hold a share 90.64% in terms of revenue. New investment requires large capital, and it is difficult for small-scale enterprises to enter the industry. SiC CMP Pads have higher requirements on technology level and processing technology. At present, the market is occupied by American companies. The market is not only influenced by the price, but also influenced by the product performance. The leading companies own the advantages on better performance, more abundant product?s types, better technical and impeccable after-sales service. Consequently, they take the majority of the market share of high-end market. Looking to the future years, prices gap between different brands will go narrowing. Similarly, there will be fluctuation in gross margin.

For manufacturers that have already entered, they need to constantly raise the technical threshold to prevent more companies from entering; by reducing costs and reducing prices, they will quickly occupy the market, develop incremental customer markets, and establish market share advantages; create a brand image and lay an advantage for entering the consumer goods market. Only in this way can we have a larger market share of capital in the fierce competition.

This report is a detailed and comprehensive analysis for global SiC CMP Pads market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global SiC CMP Pads market size and forecasts, in consumption value ($ Million), sales quantity (K Pcs), and average selling prices (US$/Pcs), 2021-2032

Global SiC CMP Pads market size and forecasts by region and country, in consumption value ($ Million), sales quantity (K Pcs), and average selling prices (US$/Pcs), 2021-2032

Global SiC CMP Pads market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (K Pcs), and average selling prices (US$/Pcs), 2021-2032

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Global SiC CMP Pads market shares of main players, shipments in revenue ($ Million), sales quantity (K Pcs), and ASP (US$/Pcs), 2021-2026

The Primary Objectives in This Report Are:
To determine the size of the total market opportunity of global and key countries
To assess the growth potential for SiC CMP Pads
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global SiC CMP Pads market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include DuPont, Fujibo Group, Entegris, IVT Technologies, Hubei Dinglong, Wuxi Jizhi Electronic Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

SiC CMP Pads market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Hard Pads

Soft Pads

Market segment by Application

4 Inch SiC Wafer

6 Inch SiC Wafer

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8 Inch SiC Wafer

Major players covered

DuPont

Fujibo Group

Entegris

IVT Technologies

Hubei Dinglong

Wuxi Jizhi Electronic Technology

Market segment by region, regional analysis covers
North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe SiC CMP Pads product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of SiC CMP Pads, with price, sales quantity, revenue, and global market share of SiC CMP Pads from 2021 to 2026.

Chapter 3, the SiC CMP Pads competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the SiC CMP Pads breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

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Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026.and SiC CMP Pads market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of SiC CMP Pads.

Chapter 14 and 15, to describe SiC CMP Pads sales channel, distributors, customers, research findings and conclusion.

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Contents

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3 COMPETITIVE ENVIRONMENT: SIC CMP PADS BY MANUFACTURER

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11 MIDDLE EAST & AFRICA

12 MARKET DYNAMICS

13 RAW MATERIAL AND INDUSTRY CHAIN

14 SHIPMENTS BY DISTRIBUTION CHANNEL

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List Of Figures

LIST OF FIGURES

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LIST OF FIGURES

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